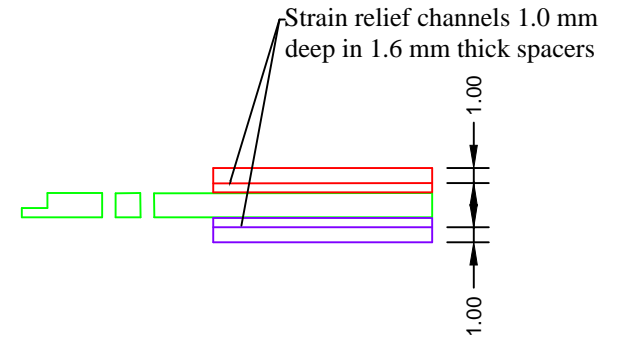
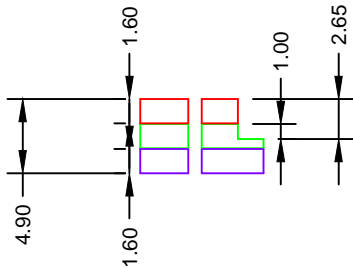


Side Profile AA'



Build Profile	
Top Spacer	1600 um
Pre-Preg	50 um
PCB	1600 um
Pre-Preg	50 um
Rear Spacer	1600 um
TOTAL THICKNESS	4900 ± 10%

Drawn. S.W	Checked. N.W	Date	Tolerances Unless Stated	Material - Standard 1.6 mm & 1.6 mm Rogers 4350
Design	Approved	08/06/2017	X.XX ± 0.10	Plating* All tracking 1 oz Cu with Ni Flash, Soft Au regions for ultrasonic bonding & immersion Ag for soldering
			X.XXX ± 0.01	Front Solder Resist - No Front Spacer- 1600 um
			Angular = ± 0.25	Rear Solder Resist - No Rear Spacer - 1600 um
			Material Thickness ± 10%	Ledge - 2650 um from top front spacer & 2250 um from bottom rear spacer.

Title.
Design W (DS) PCB with Strain Relief.

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 design@micronsemiconductor.co.uk

Scale: **2:1** | Dims In. **mm** | Drg. No. **C-2955**